

Features

- DC - 2.5 GHz
- 100 Watts
- BeO Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

Resistive Element:	Thick film
Substrate:	Beryllium oxide ceramic
Cover:	Alumina ceramic
Lead(s):	99.99% pure silver (.005" thk)

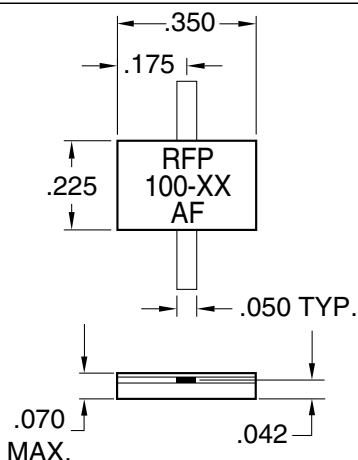
Electrical Specifications

Attenuation Value:	1, 2, 3, 4, 5, 6, 9, 10, 20 or 30 dB
Frequency Range:	DC - 2.5 GHz
Power:	100 Watts

Notes: Tolerance is ± 0.010 , unless otherwise specified. Operating temperature is -55°C to $+150^{\circ}\text{C}$ (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. Lead length 0.15" minimum.

Specifications subject to change without notice.

Outline Drawing



Note: XX denotes attenuation value.

VER. 12/5/01

Model RFP-100-XXAF

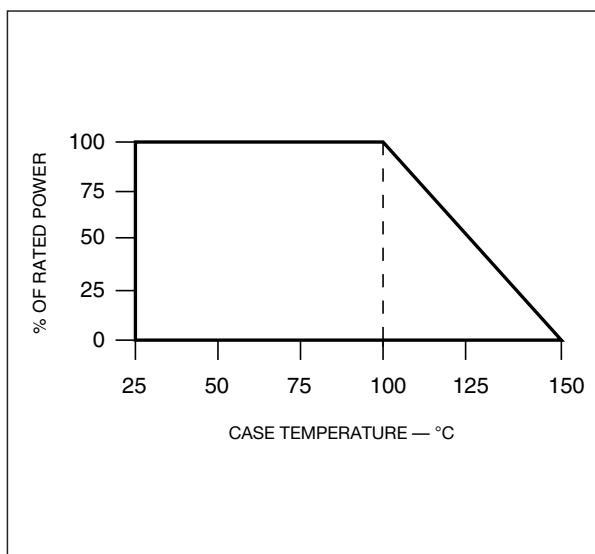
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RF Power

Specifications

PART NUMBER	ATTENUATION (dB)	TOL. (+/-dB)	POWER (WATTS)	VSWR	FREQ. (GHz)
RFP-100-1AF	1	0.40	100	1.45:1	1.0
RFP-100-2AF	2	0.40	100	1.40:1	1.0
RFP-100-3AF	3	0.40	100	1.35:1	1.0
RFP-100-4AF	4	0.30	100	1.30:1	1.0
RFP-100-5AF	5	0.30	100	1.25:1	1.0
RFP-100-6AF	6	0.30	100	1.20:1	1.0
RFP-100-9AF	9	0.30	100	1.20:1	1.0
RFP-100-10AF	10	0.75	100	1.25:1	2.0
RFP-100-20AF	20	0.50	100	1.20:1	2.5
RFP-100-30AF	30	2.00	100	1.30:1	2.0

Power Derating



Suggested Mounting Procedures

The diagrams illustrate the correct and incorrect ways to mount the device. The left side shows 'SUGGESTED STRESS RELIEF METHODS' with two scenarios: 'BOARD LOWER THAN LEAD' and 'BOARD EVEN WITH LEAD'. The right side shows 'NOT RECOMMENDED APPLICATION' with two scenarios: 'BOARD LOWER THAN LEAD' and 'BOARD HIGHER THAN LEAD'. A dimension of .025 MIN. (2 PLACES) is indicated for the lead length. Scale lines are provided for both sections.

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Position device on mounting surface and solder in place using an indalloy type or an SN63 type solder.
3. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).